

Title (en)

LEAD FREE COPPER ALLOY AND USE OF THE LEAD FREE COPPER ALLOY

Title (de)

BLEIFREIE KUPFERLEGIERUNG SOWIE VERWENDUNG DER BLEIFREIEN KUPFERLEGIERUNG

Title (fr)

ALLIAGE DE CUIVRE SANS PLOMB ET UTILISAGE DE L'ALLIAGE DE CUIVRE SANS PLOMB

Publication

EP 3985136 A1 20220420 (DE)

Application

EP 21201428 A 20211007

Priority

DE 102020127317 A 20201016

Abstract (en)

[origin: MX2021012641A] The present invention relates to a lead-free copper alloy, comprising: 70.0 to 83.0% by weight of Cu, 2.0 to 2.9% by weight of Si, 0.05 to 0.10% by weight of P, 0.01 to less than 0.30% by weight of Sn, the rest: Zn and unavoidable impurities.

Abstract (de)

Die Erfindung betrifft eine bleifreie Kupferlegierung, umfassend: 70,0 bis 83,0 Gew.% an Cu, 2,0 bis 2,9 Gew.% an Si, 0,05 bis 0,10 Gew.% an P, 0,01 bis weniger als 0,30 Gew.% an Sn, Rest: Zn und unvermeidbare Verunreinigungen.

IPC 8 full level

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CPC (source: CN EP US)

C21D 1/26 (2013.01 - CN); **C22C 9/04** (2013.01 - CN EP US); **C22F 1/08** (2013.01 - CN); **C22F 1/08** (2013.01 - EP)

Citation (applicant)

- EP 1777305 B1 20100922 - MITSUBISHI SHINDO KK [JP]
- EP 1502964 B1 20060301 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1777308 B1 20111214 - MITSUBISHI SHINDO KK [JP]
- DE 10308778 B3 20040812 - WIELAND WERKE AG [DE]
- EP 1600515 A2 20051130 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1600516 A2 20051130 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1559802 A1 20050803 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1600517 A2 20051130 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1045041 A1 20001018 - SAMBO COPPER ALLOY CO LTD [JP]
- EP 1508626 A1 20050223 - SAMBO COPPER ALLOY CO LTD [JP]

Citation (search report)

- [I] EP 2634275 A1 20130904 - MITSUBISHI SHINDO KK [JP]
- [A] CN 105603250 A 20160525 - UNIV SHANGHAI SCIENCE & TECH

Citation (third parties)

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US 2007062615 A1 20070322 - OISHI KEIICHIRO [JP]

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Designated extension state (EPC)

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